L Numbe	r Hits	Search Text	I DD	
27	7		DB	Time stamp
28	5	("4982265" "5046238" "5334875"	USPAT	2003/03/18 12:42
1		["5646446" "5776797") PN	USPAT	2003/03/18 12:45
31	12	5776797.URPN.	HODZE	
34	5	("3039177" "3467892" "4629409"	USPAT	2003/03/18 12:45
		"4833568" "5289346").PN.	USPAT	2003/03/18 14:09
35	57	5289346.URPN.		
42	41305	semiconductor and (stacking stacked)	USPAT	2003/03/18 14:09
		(Bedeking Stacked)	USPAT;	2003/03/18 14:37
			US-PGPUB;	
			EPO; JPO;	
43	35232	(semiconductor and (stacking stacked)) and	DERWENT	
		(method process)		2003/03/18 14:38
		1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	US-PGPUB;	
			EPO; JPO;	
44	215	((semiconductor and (stacking stacked))	DERWENT	
		and (method process)) and ((plexible near1	USPAT;	2003/03/18 14:42
		(tape substrate)) (bonding near tape))		
		(boliding hear tape))	EPO; JPO;	
45	63	(((semiconductor and (stacking stacked))	DERWENT	
1		and (method process)) and ((plexible near1	USPAT;	2003/03/18 14:40
	.	(tape substrate)) (bonding near tape)))		
		and (bending bended)	EPO; JPO;	
46	23	((plexible near1 (tape substrate))	DERWENT	.
		(bonding near tape)) with (bending bended)	USPAT;	2003/03/18 14:41
		(bending hear cape)) with (bending bended)	US-PGPUB;	
			EPO; JPO;	
47	2	(((semiconductor and (stacking stacked))	DERWENT	
		and (method process)) and ((plexible near)	USPAT;	2003/03/18 14:41
		(tape substrate)) (bonding near tape)))	US-PGPUB;	
		and ((plexible near1 (tape substrate))	EPO; JPO;	
		(bonding near tape)) with (bending	DERWENT	
		bended))		
50	248	((semiconductor and (stacking stacked))		
1		and (method process)) and (((plexible	USPAT;	2003/03/18 14:43
		folded folding) near1 (tape substrate))	US-PGPUB;	
		(bonding near tape))	EPO; JPO;	
51	16	(US-5805422-\$ or US-5394303-\$ or	DERWENT	
		US-6225688-\$ or US-5776797-\$ or	USPAT;	2003/03/18 14:43
		US-5646446-\$ or US-6246114-\$ or	US-PGPUB;	
	1 1	US-5818107-\$ or US-6528353-\$ or	JPO	
	1	US-6473308-\$ or US-6462412-\$ or		
1	[]	US-6441476-\$ or US-6300679-\$ or		
	i 1 '	US-6262895-\$ or $US-6121676-$$) did an		
	1	(US-20010006252-S) did or		
		(JP-08222691-\$).did.		1
54	244	(((semiconductor and (stacking stacked))	HODAM	
		and (method process)) and ((hlevible	USPAT;	2003/03/18 14:43
		colded folding) near1 (tabe substrate))	US-PGPUB; EPO; JPO;	
İ		(Dollgring near tabe))) not //fig_5006400 6	DERWENT	
	1 6	05-5394303-\$ or US-6225688-\$ or	DEKWENT	
	1 4	18-57/6797-9 or $08-5646446-9$ or		
	į t	JS-6246114-\$ or US-5818107-\$ or		
	ال	JS-6528353-\$ or $US-6473308-$$ or		
	1 0	JS-6462412-\$ or US-6441476-\$ or	i	
	L	IS-6300679-\$ or $IIS-6262895-$$ or		
	0	S-6121676-\$).did. or		
	(US-20010006252-\$).did. or		1
) (JP-08222691-\$).did.)		
55	2 ("6049123" "6102710") PN	USPAT	2002/02/12
56	0 6	469377.URPN.	USPAT	2003/03/18 14:48
57	0 6	444921.URPN.	USPAT	2003/03/18 14:49
			ODEWI	2003/03/18 14:55

58	4	4 ("3795037" "4271588" "4547834"		
1	_	WACA0170W WACA01700 4047004	USPAT	2003/03/18 14:5
		W4700000		
		1400701011		
		WEO.CEO.CE.		
		WE 1 0 0 1 CO		
		"5199163" "5264065" "5306571"		
		"53/8306" "5426072" "5428190"		
		"5429879" "5474458" "5478972"		
		"5483421" "5499444" "5530288"		
		"5544017" "5573428" "5575630"		
		"5590460" "5591519" "5627405"		
		"5659153" "5665650" "5678287"		
		WE COOOCT !!		
		1 3691041"		
59				·
60	7		USPAT	2003/03/18 14:58
	'	1 1 00 1 0 1 1 0 4 4 0 0 2 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT	2003/03/18 14:58
		"5815372" "5933712" "5995379"		2003/03/18 14:38
51	1.0	("6005292").PN.		
52	10		USPAT	2002/02/12 15
	3		USPAT	2003/03/18 15:00
3	3	\ 0432/29" "5466634" "5578516"\ DN		2003/03/18 15:02
54	5	1 01210/0.URPN.	USPAT	2003/03/18 15:03
55	12	("5008496" "5229916" "5345205"	USPAT	2003/03/18 15:08
		"5783870" "5790380" "5805422"	USPAT	2003/03/18 15:09
		"6014316" "6061245" "6121676"		
	- 1	"6172418" "6177721" "6121676"		
6	12	"6172418" "6177721" "6208521").PN.		
7	0	6496544 TID DV	USPAT	2003/03/18 15:09
8	12		USPAT	2003/03/18 15:11
•	12		USPAT	2003/03/18 15:11
		"5046446" "5773882" "5783870"	001111	2003/03/18 15:11
		"5949142" "5969426" "6071755"		
1	1	"60/5287" "6208521" "6324067"\ DN		
T.	12	("D±09535" "5450283" "5570525"	HCDAM	0000 100 1
		"5646446" "5773882" "5783870"	USPAT	2003/03/18 15:11
		"5949142" "5969426" "6071755"		
		"6075287" "6208521" "6324067").PN.		
4	3	6281577.URPN.		
5	17	("4983533" "5006005" "504.64	USPAT	2003/03/18 15:14
	1	("4983533" "5006925" "5016138" "5224023" "5313096" "5345205"	USPAT	2003/03/18 15:14
		"5224023" "5313096" "5345205"		15.14
		"5397916" "5448511" "5514907"		
		"5602420" "5604377" "5648684"		
		"5656856" "5754405" "5790390"		
;		"61216/6" "6208521").PN		
	23	5448511.URPN.	II C D A M	
l	4	("3766439" "5117282" "5313416"	USPAT	2003/03/18 15:15
		"5335145").PN.	USPAT	2003/03/18 15:17
	44	5224023.URPN.		
	o l	6507106.URPN.	USPAT	2003/03/18 15:19
2	2	("5224023" "5646446").PN.	USPAT	2003/03/18 15:20
		1 3046446").PN.	USPAT	2003/03/18 15:20